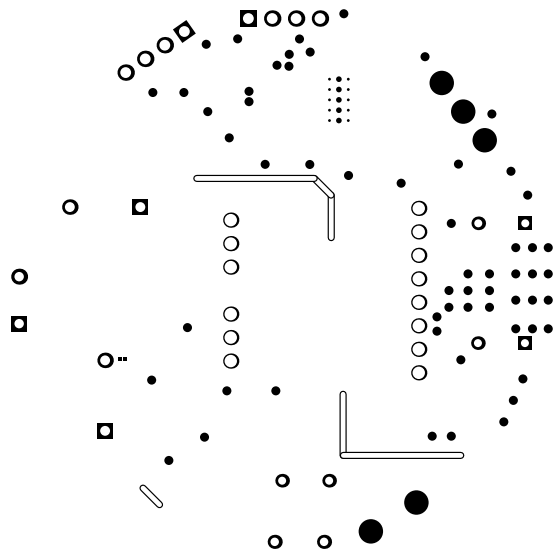
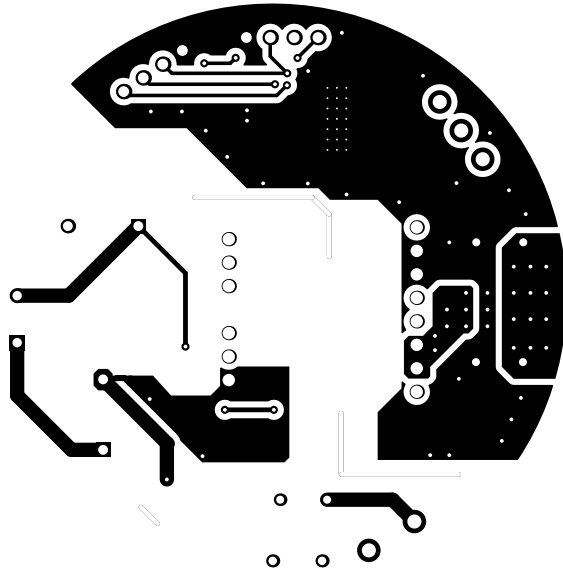


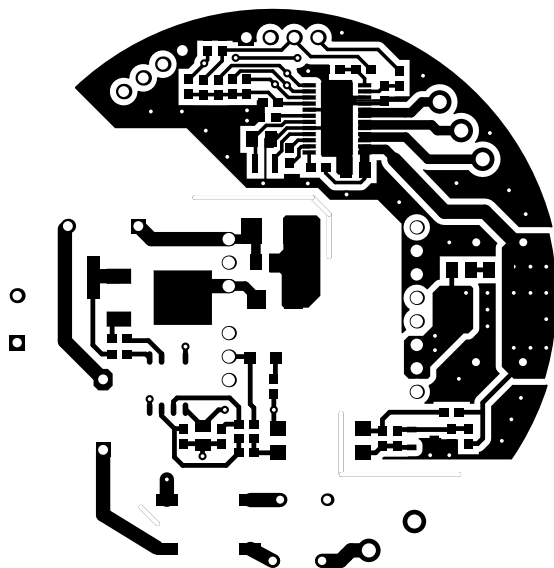
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01417		
PLOT NAME = Top Overlay	GENERATED : 3/23/2017 3:18:32 PM	TEXAS INSTRUMENTS	



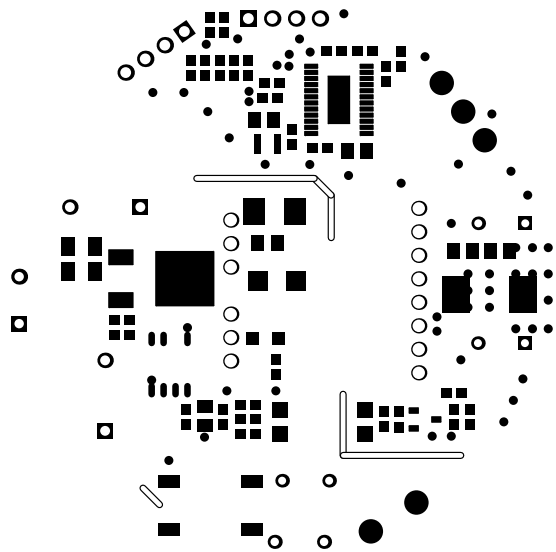
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01417		
PLOT NAME = Top Solder Mask	GENERATED : 3/23/2017 3:18:33 PM	TEXAS INSTRUMENTS	



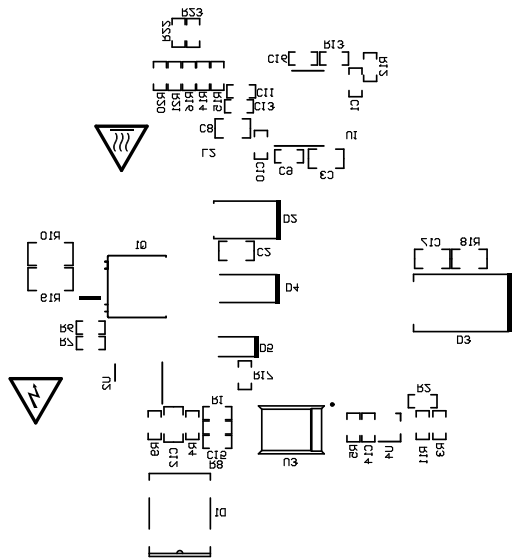
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 01417		
PLOT NAME = Top Layer	GENERATED : 3/23/2017 3:18:34 PM	TEXAS INSTRUMENTS	



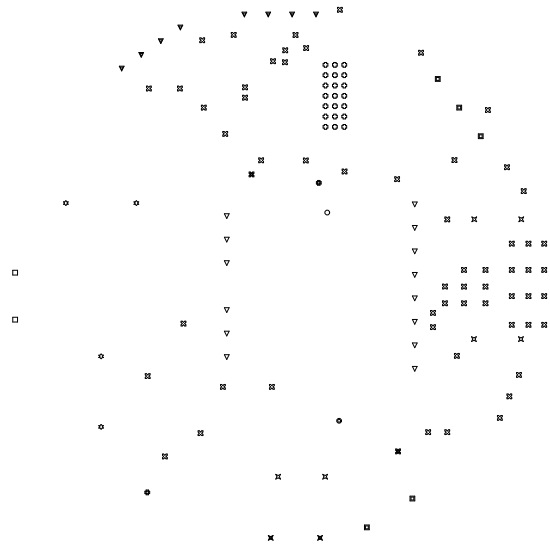
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 01417		
PLOT NAME = Bottom Layer	GENERATED : 3/23/2017 3:18:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01417		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/23/2017 3:18:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01417		
PLOT NAME = Bottom Overlay	GENERATED : 3/23/2017 3:18:37 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	21	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	58	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
▽	8	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
▽	14	51.97mil (1.320mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	5	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	20.00mil (0.508mm)	NPTH	Slot	Top Layer - Bottom Layer	
○	1	20.00mil (0.508mm)	NPTH	Slot	Top Layer - Bottom Layer	
⊗	1	20.00mil (0.508mm)	NPTH	Slot	Top Layer - Bottom Layer	
⊗	2	20.00mil (0.508mm)	NPTH	Slot	Top Layer - Bottom Layer	
	126 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01417		
PLOT NAME = Drill Drawing	GENERATED : 3/23/2017 3:18:38 PM	TEXAS INSTRUMENTS	

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01417	REV: E1	SVN REV: Not In VersionControl
LAYER NAME =	TID #: 01417		
PLOT NAME = Board Dimensions	GENERATED : 3/23/2017 3:18:39 PM		TEXAS INSTRUMENTS

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